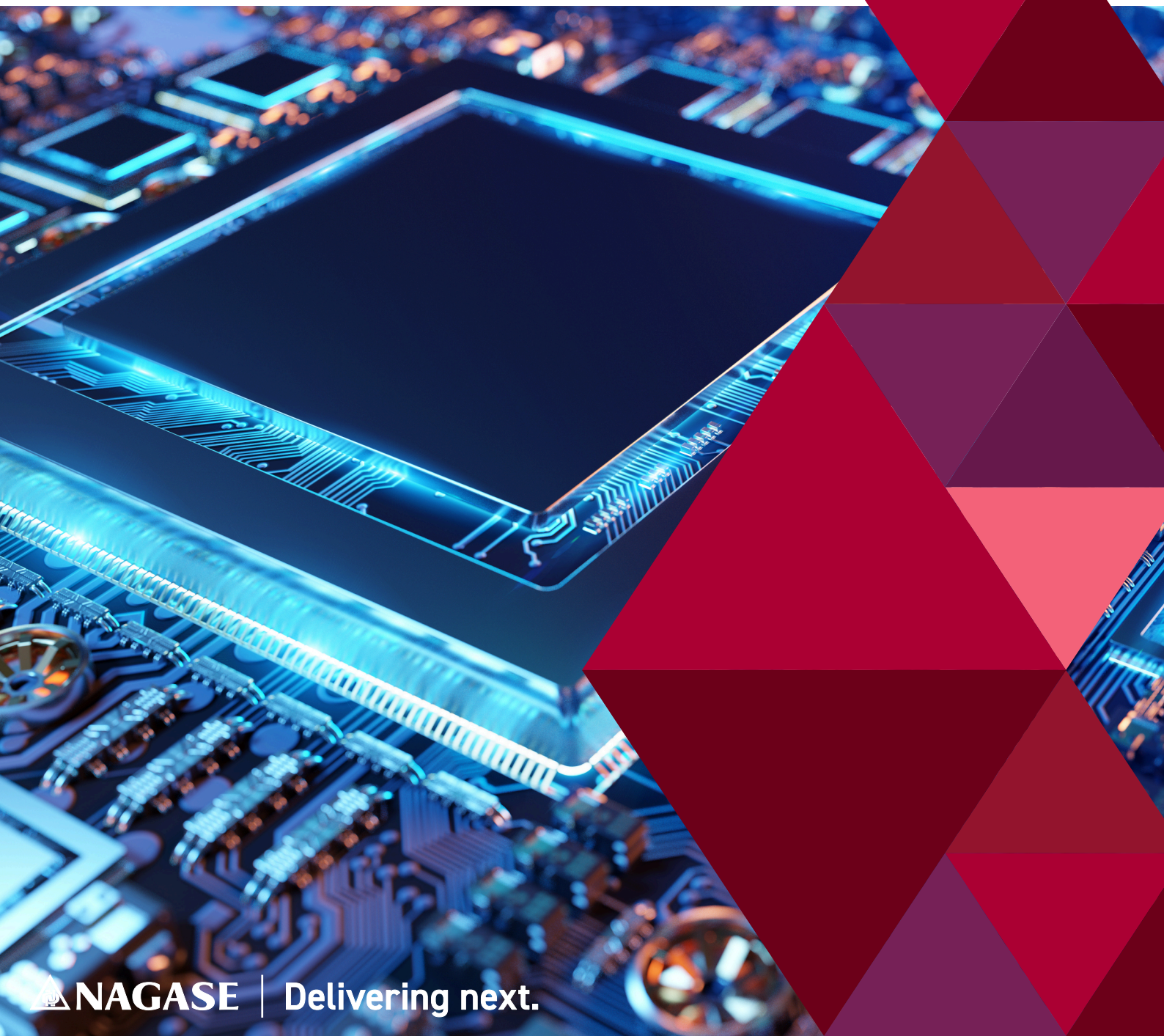




Materials for Power Devices and Electronic Components

# Molding Compounds

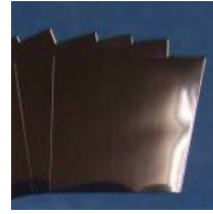


# Molding Compounds for Next-Generation Power Devices

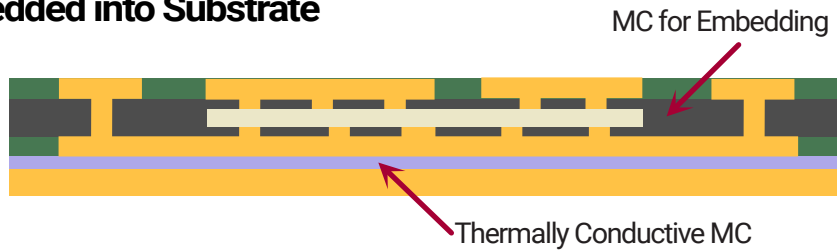
New Molding Compound Concept

## Features

- » Low electrical loss & low inductance
- » Extremely good embedding performance
- » High thermal reliability

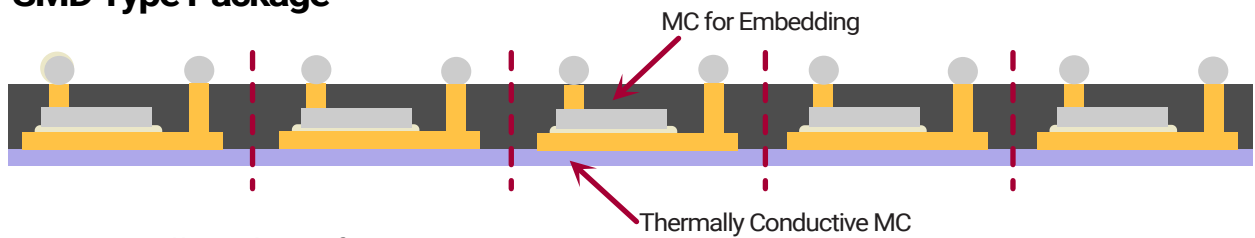


## Power Dies Embedded into Substrate



- » Die Embedding through Mold Compound with high reliability
- » Process: Compression, Laminating, Pressing

## BGA / SMD Type Package



- » BGA type small Package for SMT
- » Process: WLP / PLP by compression

# Rigid Thermally Conductive Layer by Mold Method

High Thermal Liquid Mold Compound

## Features

- » Advanced Thermal Conductivity & Insulation
- » Thermal conductivity up to 6.2 W/mK
- » LMC: Design flexibility
- » a-SMC: Higher thermal conductivity



Power Device, E-Component

